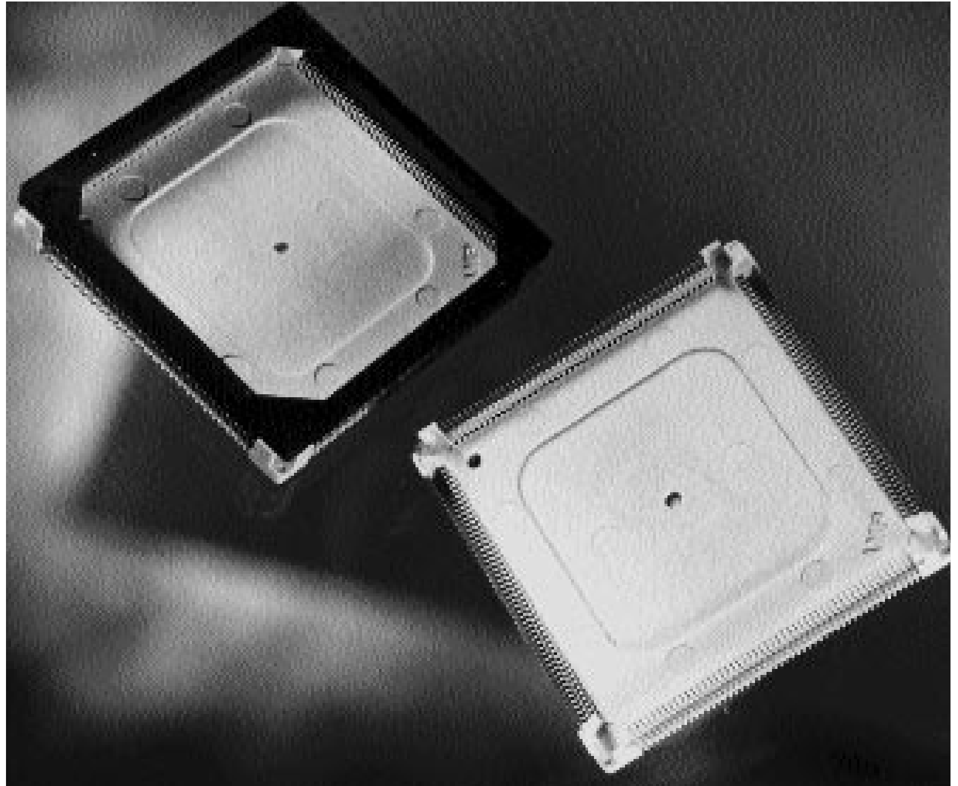
80- and 196-Position MICRO-PITCH Surface Mount Socket

- Low .290-Inch Profile Above the Board Maximizes Packaging Real Estate
- Scalloped Foot Increases Solder Joint Reliability
- Three Footprint Options Allow Design Flexibility
- Surface-Mount Configuration Facilitates Manufacturing Process Efficiency



The AMP 196-position MICRO-PITCH surface-mount socket was designed for JEDEC-approved plastic quad flat pack (PQFP) packages with preformed, gull-wing leads on .025-inch contact centerline spacing. It offers a low .290-inch profile above the printed circuit board and is also available in an 80-position version.

The socket's contacts feature a scalloped foot that increases solder joint reliability. The scalloped area at the base of each contact forms strong solder fillets during infrared, vapor phase or forced air convection reflow soldering. This design, available in three footprint options, accommodates thermal differences between the device package and the PCB.

Insulating barriers in the socket ensure accurate lead placement during package installation; once in place, the socket's cover secures the package.

The socket offers contact self-inductance of 1.8 nanohenries and contact resistance of 12 milliohms maximum. Capacitance between adjacent contacts is .6 picofarad. Mating force is approximately one pound per contact.

HOST SYSTEMS AND PROCESSORS SUPPORTED:

The 196-position socket supports Intel i960® Cx microprocessors. The 80-position socket supports i960 Sx microprocessors.

CONTACT:

AMP Product Information Center
P.O. Box 3608
Harrisburg, PA 17105
Phone: (800) 522-6752
(717) 564-0100
FAX: (717) 986-7575
For international contacts see Appendix B.

AMP